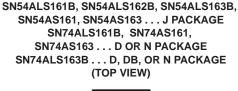
SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163 SN74ALS161B, SN74ALS163B, SN74AS161, SN74AS163 SYNCHRONOUS 4-BIT DECADE AND BINARY COUNTERS SDAS276A - DECEMBER 1994 - REVISED JULY 2000

- Internal Look-Ahead Circuitry for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- Package Options Include Plastic Small-Outline (D) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Standard Plastic (N) and Ceramic (J) DIPs

description

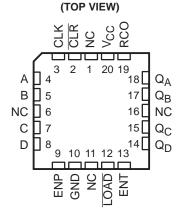
These synchronous, presettable, 4-bit decade and binary counters feature an internal carry look-ahead circuitry for application in high-speed counting designs. The SN54ALS162B is a 4-bit decade counter. The 'ALS161B, 'ALS163B, 'AS161, and 'AS163 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidentally with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock input waveform.

These counters are fully programmable; they can be preset to any number between 0 and 9 or 15. Because presetting is synchronous, setting up a low level at the load (\overline{LOAD}) input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.



	_			
CLR [1	U	16] v _{cc}
CLK [2		15] RCO
Α[14] Q _A
в[13] Q _B
с[5		12] Q _C
D [11] Q _D
ENP [7		10] ENT
GND [8		9] LOAD

SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163... FK PACKAGE



NC – No internal connection

The clear function for the 'ALS161B and 'AS161 devices is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, LOAD, or enable inputs. The clear function for the SN54ALS162B, 'ALS163B, and 'AS163 devices is synchronous, and a low level at CLR sets all four of the flip-flop outputs low after the next clock pulse, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to CLR to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP and ENT inputs and a ripple-carry (RCO) output are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. RCO, thus enabled,



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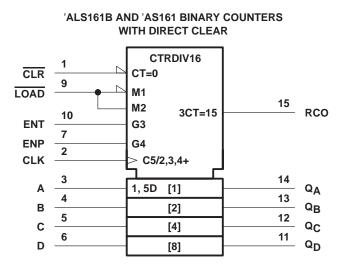
description (continued)

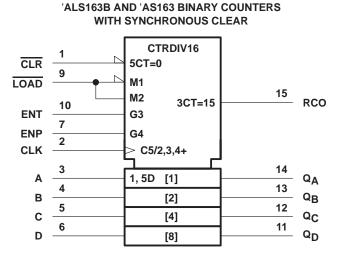
produces a high-level pulse while the count is maximum (9 or 15, with Q_A high). The high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or LOAD) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

The SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, and SN54AS163 are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS161B, SN74ALS163B, SN74AS161, and SN74AS163 are characterized for operation from 0°C to 70°C.

logic symbols[†]





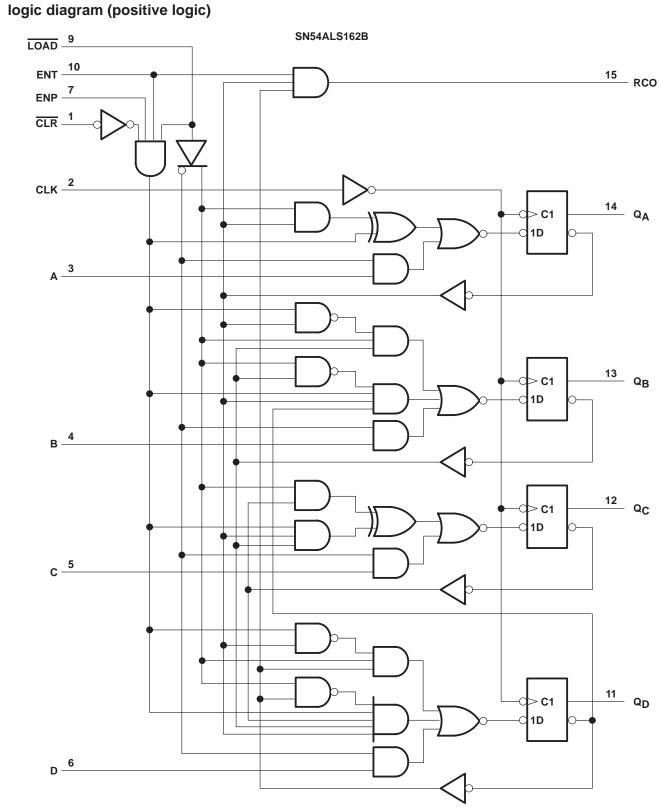
SN54ALS162B DECADE COUNTER WITH SYNCHRONOUS CLEAR

CLR LOAD ENT ENP CLK	1 9 10 7 2	CTRDIV10 5CT=0 M1 M2 3CT=9 G3 G4 > C5/2,3,4+	15_	RCO
А	3	1, 5D [1]	14	QA
В	4	[2]	13	QB
	5		12	
С		[4]		QC
D	6	[8]	11	QD

[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, and N packages.



SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163 SN74ALS161B, SN74ALS163B, SN74AS161, SN74AS163 SYNCHRONOUS 4-BIT DECADE AND BINARY COUNTERS SDAS276A – DECEMBER 1994 – REVISED JULY 2000

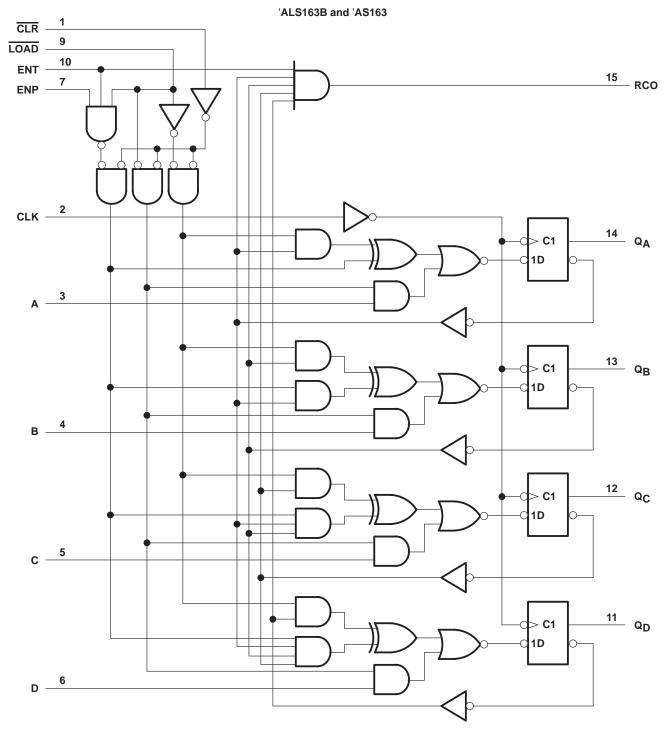


Pin numbers shown are for the J package.



SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163 SN74ALS161B, SN74ALS163B, SN74AS161, SN74AS163 SYNCHRONOUS 4-BIT DECADE AND BINARY COUNTERS SDAS276A - DECEMBER 1994 - REVISED JULY 2000

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, and N packages. 'ALS161B and 'AS161 synchronous binary counters are similar; however, CLR is asynchronous.



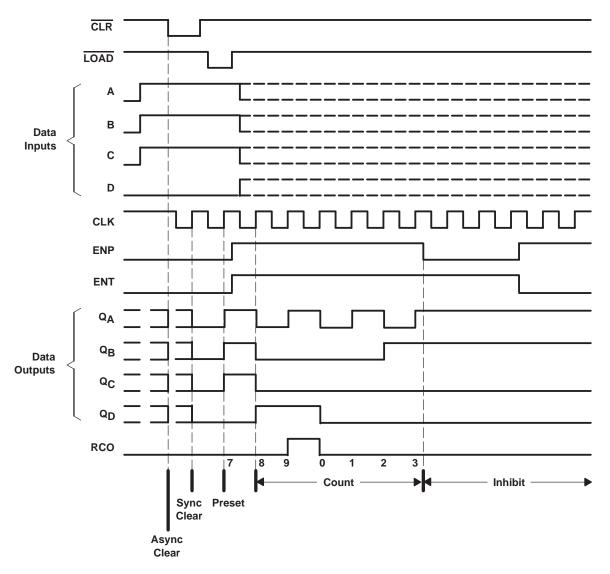
SN54ALS161B, SN54ALS162B, SN54ALS163B, SN54AS161, SN54AS163 SN74ALS161B, SN74ALS163B, SN74AS161, SN74AS163 SYNCHRONOUS 4-BIT DECADE AND BINARY COUNTERS SDAS276A - DECEMBER 1994 - REVISED JULY 2000

typical clear, preset, count, and inhibit sequences

SN54ALS162B

The following sequence is illustrated below:

- 1. Clear outputs to zero (SN54ALS162B is synchronous)
- 2. Preset to BCD 7
- 3. Count to 8, 9, 0, 1, 2, and 3
- 4. Inhibit



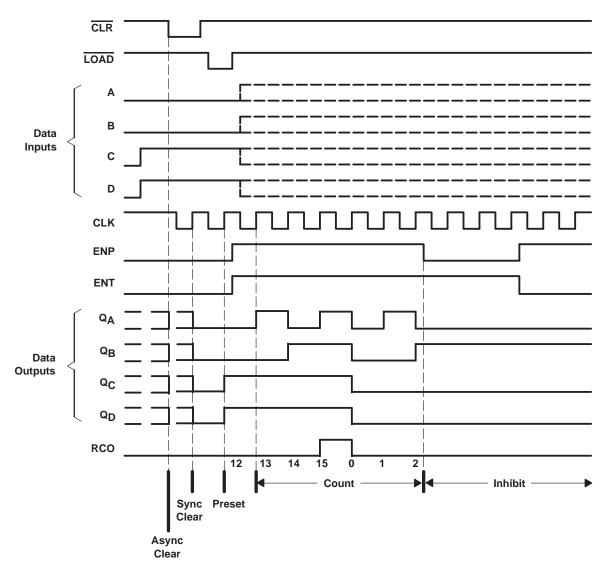
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typical clear, preset, count, and inhibit sequences

'ALS161B, 'AS161, 'ALS163B, and 'AS163

The following sequence is illustrated below:

- 1. Clear outputs to zero ('ALS161B and 'AS161 are asynchronous; 'ALS163B and 'AS163 are synchronous.)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		
Input voltage range, V ₁		-0.5 V to 7 V
Package thermal impedance, θ_{JA} (see Note 1):	: D package	73°C/W
	DB package	82°C/W
	N package	67°C/W
Storage temperature range, T _{stg}		·65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

		SN	54ALS16 54ALS16 54ALS16	2B	-	SN74ALS161B SN74ALS163B		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS161B SN54ALS162B SN54ALS163B			SN74ALS161B SN74ALS163B			UNIT
		E E E E E E E E E E E E E E E E E E E		TYP‡	MAX	MIN	TYP‡	MAX	
VIK	$V_{CC} = 4.5 V,$	I _I = -18 mA			-1.5			-1.5	V
VOH	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
Ve	V _{CC} = 4.5 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.3 V	I _{OL} = 8 mA					0.35	0.5	v
lj	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
ЧΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.2			-0.2	mA
ΙΟ [§]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V			12	21		12	21	mA

[‡] All typical values are at V_{CC} = 5 V, $T_A = 25^{\circ}C$.

§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.



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timing requirements over recommended operating conditions (unless otherwise noted) (see Figure 1)

				SN54AL SN54AL SN54AL	S162B	SN74AL SN74AL		UNIT
				MIN	MAX	MIN	MAX	
fclock	Clock frequency	-			22		40	MHz
	Pulse duration	CLR high or low		20		12.5		ns
tw		'ALS161B	CLR low	20		15		115
		A, B, C, D		50		15		
		LOAD		20		15		
		'ALS161B	ENP, ENT	25		15		
t _{su}	Setup time, before $CLK{\uparrow}$	SN54ALS162B, 'ALS163B	ENP, ENT	20		15		ns
		'ALS161B	CLR inactive	10		10		
			CLR low	20		15		
		SN54ALS162B, 'ALS163B	CLR high	20		10		
t _h	Hold time, all synchronous inputs af	ter CLK1		0		0		ns

switching characteristics over recommended operating conditions (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	SN54ALS161B		SN74AL	S161B	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
fmax			22		40		MHz
^t PLH	CLK	RCO	5	34	5	20	ns
^t PHL	CLK	RCO	5	27	5	20	115
^t PLH	CLK	Any Q	4	19	4	15	ns
^t PHL	OLK	Any Q	6	25	6	20	115
^t PLH	ENT	RCO	3	18	3	13	ns
^t PHL	ENI	KCO	3	17	3	13	115
tou	CLR	Any Q	8	27	8	24	200
^t PHL	ULK	RCO	11	32	11	23	ns

switching characteristics over recommended operating conditions (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALS162B SN54ALS163B		SN74AL	UNIT	
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	
fmax			22		40		MHz
^t PLH	CLK	RCO	5	25	5	20	ns
^t PHL	OLK	KOO	5	25	5	20	115
^t PLH	CLK	Amu O	4	18	4	15	ns
^t PHL	OLK	Any Q	6	25	6	20	115
t _{PLH}	ENT	RCO	3	16	3	13	ns
^t PHL	LINI	- Reo	3	16	3	13	115



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recommended operating conditions

		-	N54AS16		-	SN74AS161 SN74AS163		
		MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-2			-2	mA
IOL	Low-level output current			20			20	mA
ТА	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

Р	ARAMETER	TEST CO	TEST CONDITIONS		SN54AS161 SN54AS163			SN74AS161 SN74AS163		
				MIN	TYP†	MAX	MIN	TYP†	MAX	
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
∨он		V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2			V
VOL		V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.25	0.5		0.25	0.5	V
	LOAD					0.3			0.3	
lj –	ENT	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.2			0.2	mA
	All others					0.1			0.1	
	LOAD					60			60	
Ιн	ENT	V _{CC} = 5.5 V,	V _I = 2.7 V			40			40	μA
	All others					20			20	
	LOAD					-1.5			-1.5	
ЧL	ENT	V _{CC} = 5.5 V,	$V_{I} = 0.4 V$			-1			-1	mA
	All others					-0.5			-0.5	
10‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICC		V _{CC} = 5.5 V			35	53		35	53	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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timing requirements over recommended operating conditions (see Figure 1)

				SN54A SN54A		SN74A SN74A		UNIT
				MIN	MAX	MIN	MAX	
fclock	Clock frequency				65		75	MHz
+	Pulse duration	CLR high or low		7.7		6.7		ns
tw	Fuise duration	'AS161	CLR low	10		8		115
		A, B, C, D		10		8		
		LOAD		10		8		
•	Setup time, before CLK↑	ENP, ENT		10		8		-
t _{su}	Setup time, before CLK	'AS161	CLR inactive	10		8		ns
		'AS163	CLR low	14		12		
		A3103	CLR high (inactive)	10		9		
th	Hold time, all synchronous inpu	its after CLK↑		2		0		ns

switching characteristics over recommended operating conditions (see Figure 1)

PARAMETER	FROM	то		S161	SN74A	S161	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
fmax			65*		75		MHz
	CLK	RCO (with LOAD high)	1	8.5	1	8	20
^t PLH	ULK	RCO (with LOAD low)	3	17.5	3	16.5	ns
^t PHL	CLK	RCO	2	14	2	12.5	ns
^t PLH	CLK	Any Q	1	7.5	1	7	ns
^t PHL	ULK		2	14	2	13	115
^t PLH	ENT	RCO	1.5	10	1.5	9	ns
^t PHL	ENT	KCO	1	9.5	1	8.5	115
tou	CLR	Any Q	2	14	2	13	ns
^t PHL	ULK	RCO	2	14	2	12.5	115

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating conditions (see Figure 1)

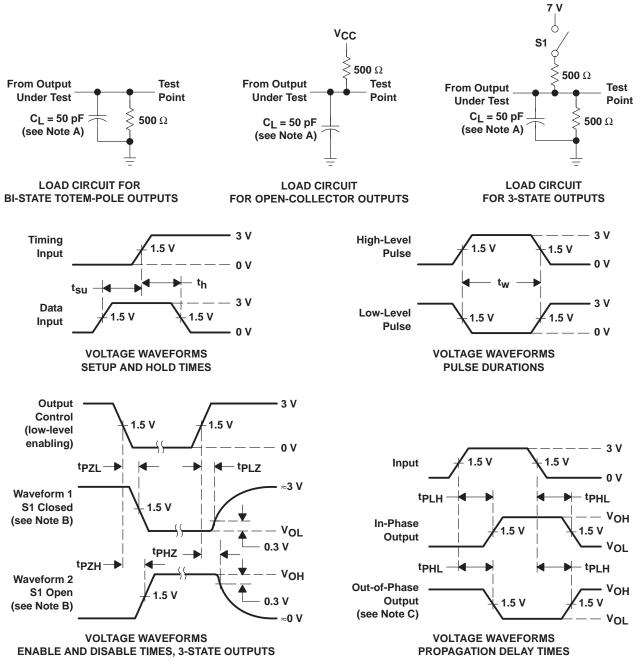
PARAMETER	FROM	то	SN54A	S163	SN74A	S163	UNIT
FARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
f _{max}			65*		75		MHz
t	CLK	RCO (with LOAD high)	1	8.5	1	8	ns
^t PLH	GER	RCO (with LOAD low)	3	17.5	3	16.5	115
^t PHL	CLK	RCO	2	14	2	12.5	ns
^t PLH	CLK	Any Q	1	7.5	1	7	ns
^t PHL	OLK	Ally Q	2	14	2	13	115
^t PLH	ENT	RCO	1.5	10	1.5	9	ns
^t PHL		KCO	1	9.5	1	8.5	115

* On products compliant to MIL-PRF-38535, this parameter is not production tested.



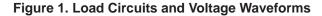
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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one input transition per measurement.

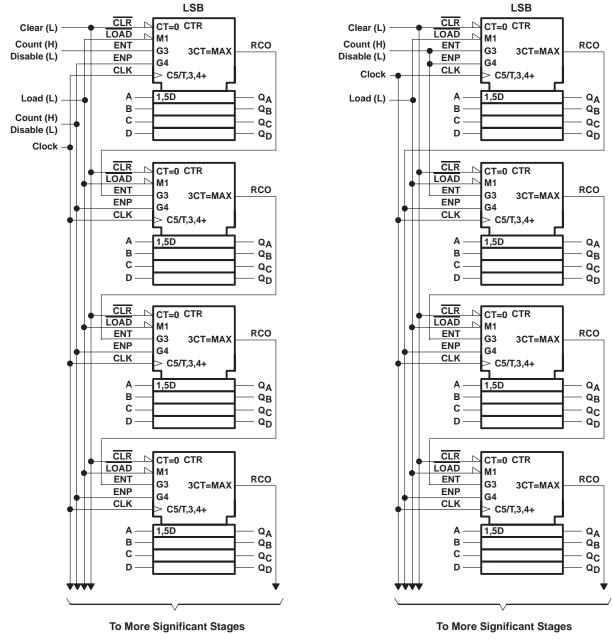


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APPLICATION INFORMATION

n-bit synchronous counters

This application demonstrates how the ripple-mode carry circuit (see Figure 2) and the carry look-ahead circuit (see Figure 3) can be used to implement a high-speed n-bit counter. The SN54ALS162B counts in BCD. The 'ALS161B, 'AS161, 'ALS163B, and 'AS163 devices count in binary. When additional stages are added, the fmax decreases in Figure 2, but remains unchanged in Figure 3.







 $f_{max} = 1/(CLK \text{ to RCO } t_{PLH}) + (ENP t_{SU})$







25-Oct-2016

PACKAGING INFORMATION

Orderable Device		Package Type		Pins	-	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
83022012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	83022012A SNJ54ALS 161BFK	Samples
8302201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302201EA SNJ54ALS161BJ	Samples
8302201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302201FA SNJ54ALS161BW	Samples
83022022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	83022022A SNJ54ALS 163BFK	Samples
8302202EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302202EA SNJ54ALS163BJ	Samples
8302202FA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/38001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 38001B2A	Samples
JM38510/38001BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 38001BEA	Samples
JM38510/38002B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 38002B2A	Samples
JM38510/38002BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 38002BEA	Samples
M38510/38001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 38001B2A	Samples
M38510/38001BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 38001BEA	Samples
M38510/38002B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 38002B2A	Samples
M38510/38002BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 38002BEA	Samples
SN54ALS161BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS161BJ	Samples
SN54ALS163BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS163BJ	Samples
SN54AS163J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device		Package Type	Package Drawing	Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sampl
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS161BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS161B	Sampl
SN74ALS161BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS161B	Sampl
SN74ALS161BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS161B	Sampl
SN74ALS161BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS161BN	Samp
SN74ALS161BN3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74ALS161BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS161B	Samp
SN74ALS163BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS163B	Sampl
SN74ALS163BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS163B	Samp
SN74ALS163BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS163B	Samp
SN74ALS163BN	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS163BN	Samp
SN74ALS163BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74ALS163BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS163B	Samp
SN74AS161N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS161N	Samp
SN74AS161NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS161	Samp
SN74AS163D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS163	Samp
SN74AS163N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS163N	Samp
SN74AS163NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS163N	Samj
SNJ54ALS161BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	83022012A SNJ54ALS 161BFK	Samj



25-Oct-2016

Orderable Device		Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54ALS161BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302201EA SNJ54ALS161BJ	Samples
SNJ54ALS161BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302201FA SNJ54ALS161BW	Samples
SNJ54ALS163BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	83022022A SNJ54ALS 163BFK	Samples
SNJ54ALS163BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302202EA SNJ54ALS163BJ	Samples
SNJ54AS161J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS161J	Samples
SNJ54AS163J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

25-Oct-2016

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS161B, SN54ALS163B, SN54AS161, SN54AS163, SN74ALS161B, SN74ALS163B, SN74AS161, SN74AS163 :

- Catalog: SN74ALS161B, SN74ALS163B, SN74AS161, SN74AS163
- Military: SN54ALS161B, SN54ALS163B, SN54AS161, SN54AS163

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS161BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS161BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ALS163BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS163BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS161NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS161BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS161BNSR	SO	NS	16	2000	367.0	367.0	38.0
SN74ALS163BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS163BNSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS161NSR	SO	NS	16	2000	367.0	367.0	38.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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